

with the arrangement of the contact substrate in the connecting position, said arranging of the substrates and said displacing of the adhesive simultaneously sealing a gap between the substrates;

10 heating the contact substrate to the connecting temperature from a rear side that is
situated opposite the terminal areas in order to reach the required connecting temperature in
the plane of the connection; and

heating the contact substrate by subjecting the substrate to laser energy to produce a
thermal connection between the terminal areas of the substrates.

Claim 14 has not been changed by this Amendment and remains as follows:

14. The method according to claim 13, wherein the rear side of the substrates are
respectively supported while the contact substrate is heated and while the contacting terminal
areas of the substrates are situated opposite one another, with the support being realized in such
a way that at least partial surface regions of the rear side are supported which lie outside of an
5 energy receiving surface that is subjected to the laser energy.

Claim 15 has not been changed by this Amendment and remains as follows:

15. The method according to claim 14, wherein the support comprises a contact surface
of a contacting device that serves for connecting or for accommodating a glass fiber.

Claim 16 has not been changed by this Amendment and remains as follows:

16. The method according to claim 15, wherein one of the substrates is subjected to a negative pressure via the contact surface in order to transfer the substrate into the connecting position.

Please cancel claims 17 - 25 without prejudice, and add the following new claims.

26. (NEW) A method for connecting a contact substrate to a carrier substrate, the method comprising the steps of:

providing a contact substrate with a terminal area;

providing a carrier substrate with a terminal area and a receiving area for receiving said contact substrate;

covering said terminal area and said receiving area of said carrier substrate with an adhesive;

placing said contact substrate on said adhesive on said carrier substrate;

moving said contact substrate through said adhesive to have said terminal area of said contact substrate move through said adhesive and cause said terminal area of said contact substrate to touch said terminal area of said carrier substrate;

heating said contact substrate on a side diametrically opposite from said carrier substrate to produce a thermal connection between said terminal areas of said substrates, said heating being performed by subjecting said contact substrate to laser energy.

27. (New) A method in accordance with claim 26, wherein:

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BV said placing and moving of said contact substrate includes arranging said substrates in a connecting position such that said terminal areas are situated opposite one another in a plane of a connection and substantially simultaneously displacing said adhesive arranged between said substrates in the plane of the connection with an arrangement of said contact substrate in the connecting position.

28. (New) A method in accordance with claim 26, further comprising:

providing a contacting device;

holding said contact substrate on said contacting device;

5 moving said contacting device to perform said placing of said contact substrate on said adhesive and to perform said moving of said contact substrate through said adhesive

29. (New) A method in accordance with claim 28, wherein:

said contacting device includes an optical fiber and defines a mouthpiece;

a vacuum is generated in said mouthpiece to perform said holding of said contact substrate;

5 said optical fiber guides said laser energy to said contact substrate.

30. (New) A method in accordance with claim 29, further comprising:

advancing said optical fiber toward said contact substrate in said mouthpiece to have